

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4442	361/704	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/13 22:21
S1	3408	257/774	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/02 18:46
S2	4073	257/778	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/02 18:58
S3	2615	257/786	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/02 19:06
S5	1	"20020171153"	US-PGPUB; USPAT	OR	OFF	2004/09/02 11:21
S6	1	"20020171153" and board with (insulat\$3 or dielectric)	US-PGPUB; USPAT	OR	ON	2004/09/02 11:57
S7	1	"5736791".pn.	US-PGPUB; USPAT	OR	ON	2004/09/02 18:28
S8	0	"20020171153"	USPAT	OR	OFF	2005/01/28 16:23
S9	1	"20020171153"	US-PGPUB; USPAT	OR	OFF	2005/01/28 16:24
S10	1	"20030122259"	US-PGPUB; USPAT	OR	OFF	2005/01/28 16:24
S11	2613	257/698	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 16:37
S12	3668	257/774	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 16:46

S13	3729	257/773	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 17:06
S14	4416	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 17:48
S15	2790	257/786	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 18:06
S16	1133	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 18:54
S17	2183	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:09
S18	2824	257/784	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:28
S19	16	"6482730".pn. or "6344696".pn. or "6245598".pn. or "6177725". pn. or "6153448".pn. or "6028354".pn. or "5990545".pn. or "5866949".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:32
S20	382070	(semiconductor or die or chip or IC) and (step or groove or recess or open\$3) with (board or PCT or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:35

S21	382018	(semiconductor or die or chip or IC) and (step or groove or recess or open\$3) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:39
S22	50028	S21 and (encapsulat\$3 or module)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:36
S23	129330	S21 and (encapsulat\$3 or mod\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:38
S24	55365	S23 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:38
S25	38727	S21 and (encapsulat\$3 or mod\$3) with (step or groove or recess or open\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:39
S26	17822	S25 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:40
S27	179232	(semiconductor or die or chip or IC) and (step or groove) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:39
S28	22292	S27 and (encapsulat\$3 or mod\$3) with (step or groove)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:39

S29	10051	S28 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:40
S30	2130	S29 and (step or groove) with (edge or peripher\$3 or perimeter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:42
S31	995	S29 and (step or groove) with (edge or peripher\$3 or perimeter) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:45
S32	26364	(semiconductor or die or chip or IC) and (step or groove) with (edge or peripher\$3 or perimeter) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:39
S33	5366	S32 and (encapsulat\$3 or mold\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:48
S34	2641	S33 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:48
S35	1423	S33 and wir\$3	USPAT	OR	ON	2005/01/28 19:53
S36	1109	S35 not S31	USPAT	OR	ON	2005/01/28 19:53
S37	2	"0050419".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:09
S38	1	"5345106".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:09
S39	1	"5661092".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
S40	1	"5808359".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
S41	1	"6166446".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
S42	1	"6249433".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10

S43	1	"6323549".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:11
S44	1	"6436550".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:11
S45	1	"6552417".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:11
S46	15012	(semiconductor or die or chip or IC) and (step\$3 or ledge) with (edge or peripher\$3 or perimeter) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:41
S47	7660	(semiconductor or die or chip or IC) and (step\$3 or ledge) with (edge or peripher\$3 or perimeter) with (board or PCB or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:42
S48	3226	(semiconductor or die or chip or IC) and (step\$3 or ledge) with (edge or peripher\$3 or perimeter) with (board or PCB or module or carrier or mount\$3)	USPAT	OR	ON	2005/01/28 20:43
S49	2703	S48 not S35	USPAT	OR	ON	2005/01/28 20:43
S50	98	S48 not S35 and (wire) and (encapsulat\$3 or mold\$3)	USPAT	OR	ON	2005/01/28 20:47
S51	58	S48 not S35 and (wiring) and (encapsulat\$3 or mold\$3)	USPAT	OR	ON	2005/01/28 20:47
S52	58	S49 and (wiring) and (encapsulat\$3 or mold\$3)	USPAT	OR	ON	2005/01/28 20:49
S53	2	S47 and (wiring) and (encapsulat\$3 or mold\$3)	JPO	OR	ON	2005/01/28 20:58
S54	2	"5964174"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:58
S55	14	"5864174"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 21:14
S56	1	"4695870".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:00
S57	1	"4855869".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:00

S58	1	"5030796".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:00
S59	1	"5175610".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:01
S60	1	"5216278".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:01
S61	1	"5264726".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:05
S62	1	"5291374".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:05
S63	1	"5311057".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
S64	1	"5319241".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
S65	1	"5436203".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
S66	1	"5450283".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
S67	1	"5455456".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
S68	1	"5467253".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
S69	1	"5477611".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
S70	1	"5496775".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
S71	1	"5508556".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
S72	1	"5528083".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
S73	1	"5621242".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S74	1	"5621242".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S75	1	"5633785".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S76	1	"5686362".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S77	1	"5789809".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
S78	1	"5866949".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08

S79	3835	257/678	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 21:34
S80	2	"5216278".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 21:34
S81	14	"5864174"	USPAT	OR	OFF	2005/07/12 16:32
S82	113410	(semiconductor or die or dice or chip or IC) and (step or stair) with (substrate or module or carrier or hous\$3 or board or tape)	USPAT	OR	ON	2005/07/12 16:35
S83	46679	(semiconductor or die or dice or chip or IC) same (step or stair) with (substrate or module or carrier or hous\$3 or board or tape)	USPAT	OR	ON	2005/07/12 16:35
S84	7032	(semiconductor or die or dice or chip or IC) same (step or stair) with (substrate or module or carrier or hous\$3 or board or tape) with (conductive or wiring)	USPAT	OR	ON	2005/07/12 16:35
S85	1171	(semiconductor or die or dice or chip or IC) same (step or stair) with (substrate or module or carrier or hous\$3 or board or tape) with (conductive or wiring) and wire near bonding	USPAT	OR	ON	2005/07/12 19:08
S86	1	"4707724".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:53
S87	1	"4835120".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:54
S88	1	"4906802".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:54
S89	1	"5065281".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:54
S90	1	"5083189".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:54
S91	1	"5136471".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:55
S92	1	"5083189".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:55
S93	1	"5157588".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:55

S94	1	"5225499".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:55
S95	1	"5249101".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:56
S96	1	"5252783".PN.	USPAT; USOCR	OR	OFF	2005/07/12 18:56
S97	1	"6841857"	USPAT	OR	ON	2005/07/12 19:11
S98	2	"0050419".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:08
S99	1	"5345106".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:08
S100	1	"5661092".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:08
S101	1	"5808359".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:09
S102	1	"6166446".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:09
S103	1	"6249433".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:09
S104	1	"6323549".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:10
S105	1	"6436550".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:10
S106	1	"6552417".PN.	USPAT; USOCR	OR	OFF	2005/07/12 19:10
S107	262	"5216278"	USPAT	OR	ON	2005/07/12 19:11